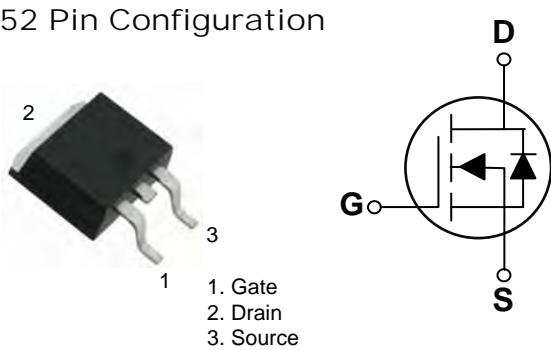


## 100V N-Channel MOSFETs

### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### TO-252 Pin Configuration



BVDSS	RDS(ON)	ID
100V	200mΩ	8A

### Features

- 100V, 8A,  $RDS(ON) = 200m\Omega$  @  $VGS = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed

### Applications

- Networking
- Load Switch
- LED applications

### Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	8	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	4.8	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	32	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	32	W
	Power Dissipation – Derate above 25°C	0.256	W/°C
$T_{STG}$	Storage Temperature Range	-50 to 150	°C
$T_J$	Operating Junction Temperature Range	-50 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to case		3.8	°C/W



# FTK0910D

## 100V N-Channel MOSFETs

Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	100	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.10	---	$\text{V}/^\circ\text{C}$
$I_{\text{DSs}}$	Drain-Source Leakage Current	$V_{\text{DS}}=100\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=80\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=125^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$

### On Characteristics

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}$ , $I_D=2\text{A}$	---	160	200	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=1\text{A}$	---	170	210	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D = 250\mu\text{A}$	1.2	1.8	2.5	V
			---	-4	---	$\text{mV}/^\circ\text{C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_D=1\text{A}$	---	5	---	S

### Dynamic and switching Characteristics

$Q_g$	Total Gate Charge <sup>2,3</sup>	$V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=2\text{A}$	---	13.4	21	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>2,3</sup>		---	2.9	6	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>2,3</sup>		---	1.7	4	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>2,3</sup>	$V_{\text{DD}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=3.3\Omega$ $I_D=1\text{A}$	---	1.6	3	ns
$T_r$	Rise Time <sup>2,3</sup>		---	6.6	13	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>2,3</sup>		---	11.5	22	
$T_f$	Fall Time <sup>2,3</sup>		---	3.6	7	
$C_{\text{iss}}$	Input Capacitance		---	820	1190	pF
$C_{\text{oss}}$	Output Capacitance	$V_{\text{DS}}=50\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	35	55	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	20	30	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	1.3	2.6	$\Omega$

### Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	8	A
	Pulsed Source Current		---	---	16	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\text{us}$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

## 100V N-Channel MOSFETs

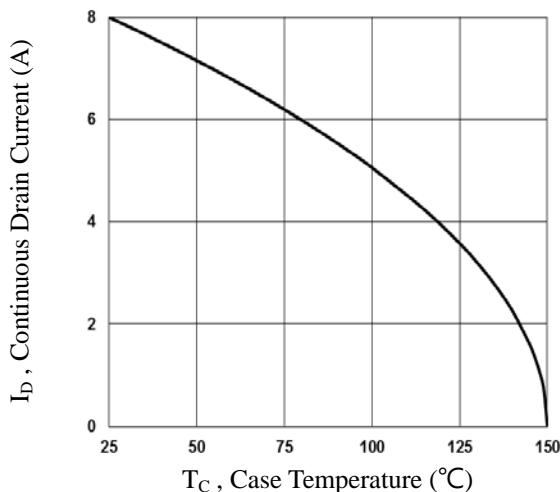


Fig.1 Continuous Drain Current vs.  $T_C$

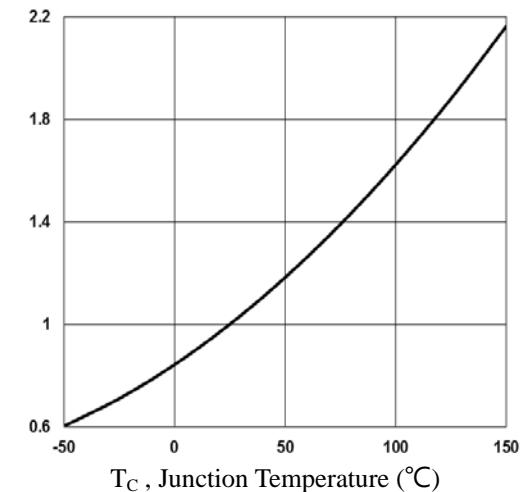


Fig.2 Continuous Drain Current vs.  $T_C$

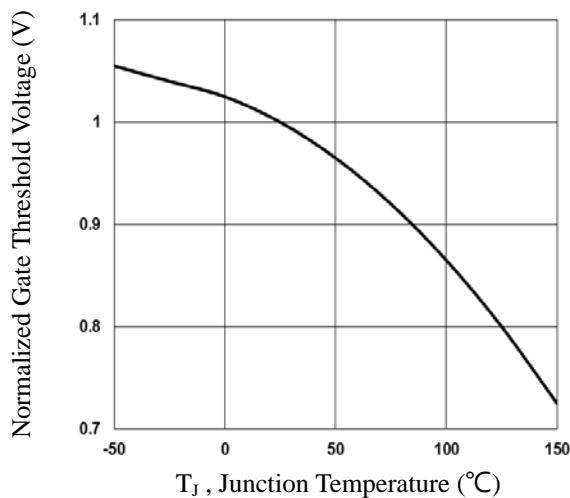


Fig.3 Normalized  $V_{th}$  vs.  $T_J$

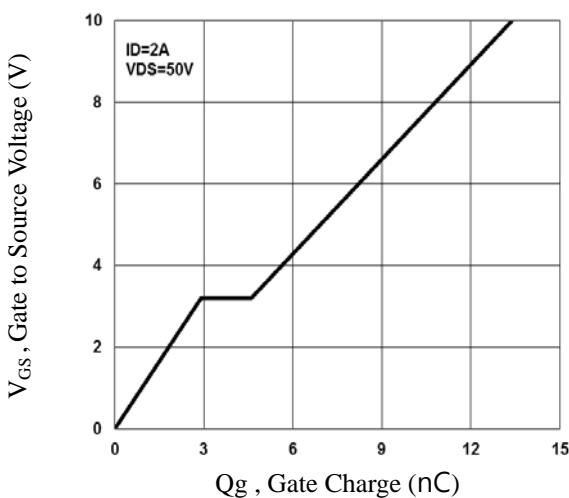


Fig.4 Gate Charge Waveform

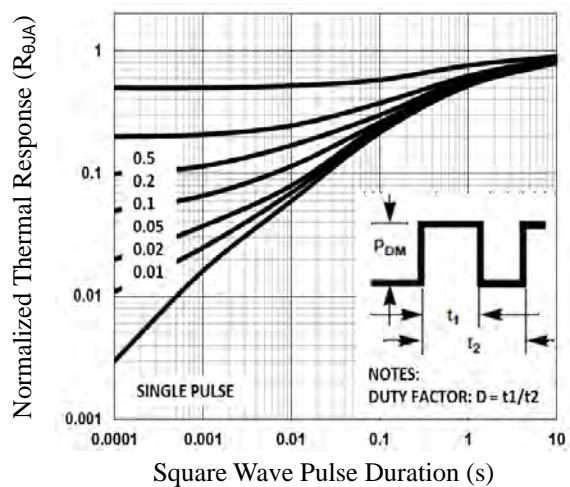


Fig.5 Normalized Transient Impedance

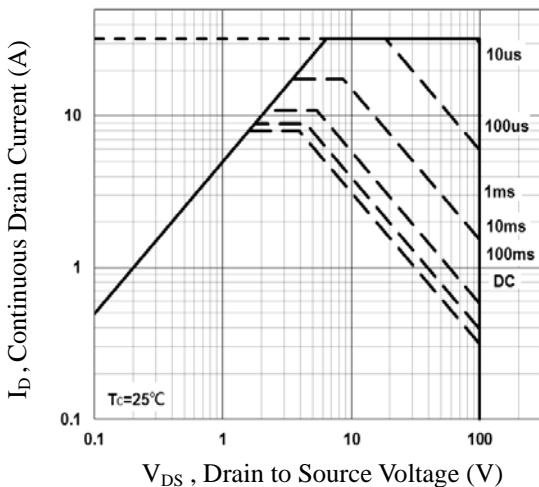


Fig.6 Maximum Safe Operation Area

## 100V N-Channel MOSFETs

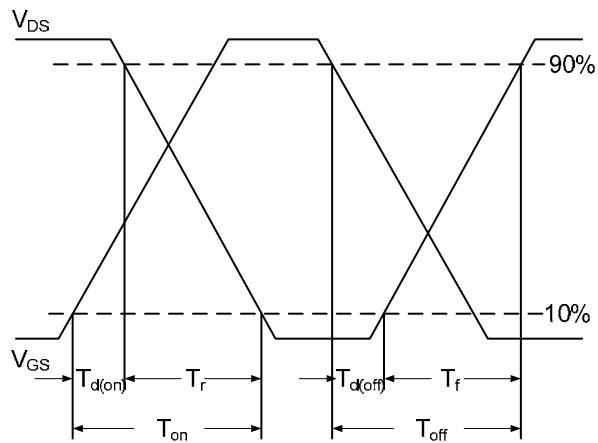


Fig.7 Switching Time Waveform

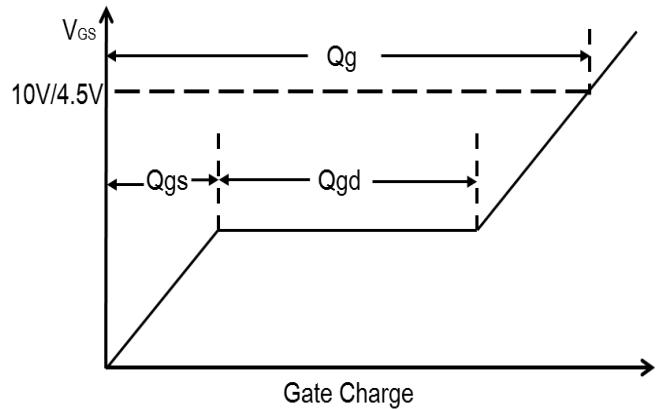
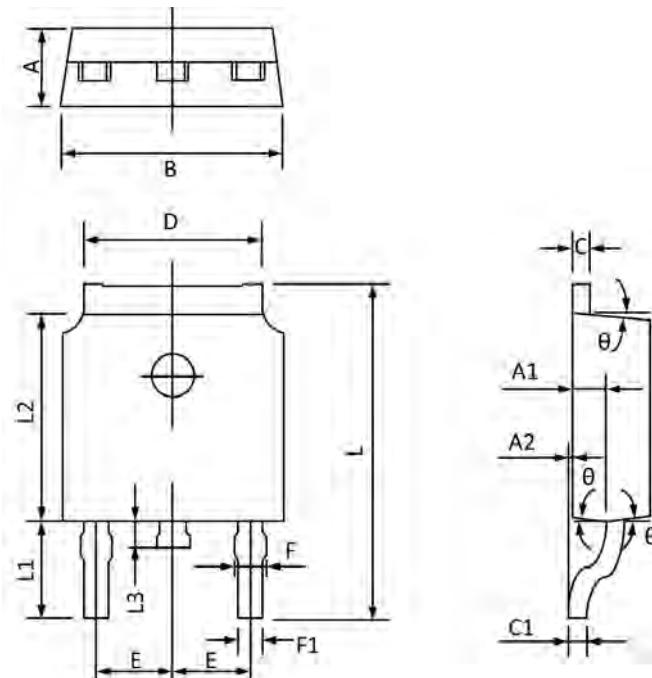


Fig.8 Gate Charge Waveform

## 100V N-Channel MOSFETs

## TO-252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	2.20	2.40	0.087	0.094
A1	0.91	1.11	0.036	0.044
A2	0.00	0.15	0.000	0.006
B	6.50	6.70	0.256	0.264
C	0.46	0.580	0.018	0.230
C1	0.46	0.580	0.018	0.030
D	5.10	5.46	0.201	0.215
E	2.186	2.386	0.086	0.094
F	0.74	0.94	0.029	0.037
F1	0.660	0.860	0.026	0.034
L	9.80	10.40	0.386	0.409
L1	2.9REF		0.114REF	
L2	6.00	6.20	0.236	0.244
L3	0.60	1.00	0.024	0.039
θ	3°	9°	3°	9°